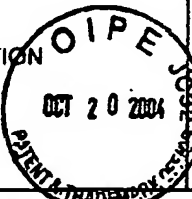


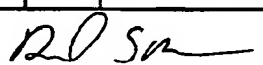


Subst. Form PTO-1449 INFORMATION DISCLOSURE CITATION IN AN APPLICATION (Use several sheets if necessary)				Docket Number (Optional) 56247-235 (CSLL-662CP)		Application Number 10/642,315	
				Applicant Sawyer, et al.		Filing Date 8/15/2003	
U. S. Patent Documents				Group Art Unit 2813			

EXAMINER INITIAL	REF	DOCUMENT NUMBER	DATE	NAME	CLASS	SUBCLASS	FILING DATE IF APPROPRIATE
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						YES	NO

OTHER DOCUMENTS (Including Author, Title, Date, Pertinent Pages, Etc.)	
	Copy of International Search Report PCT/US02/00015
	C1 Moore DF, "Silicon-on insulator material for sensors and accelerometers" Silicon Fabricated Inertial instruments, 9/1-9/5 (December 1996) C2 Syms RRA et al., "Surface tension powered self-assembly of 3D MOEMS devices using DRIE of bonded silicon-on-insulator wafers." IEEE Seminar on Demonstrated Micromachining Technologies for Industry, 1/1-1/6 (March 2000) C3 Yamamoto T et al. "Capacitive accelerometer with high aspect ratio single crystalline silicon microstructure using SOI structure with polysilicon-based interconnect technique." Micro Electro Mechanical Systems, 515-519 (January 2000) C4 Martin A. Schmidt, "Wafer-to-Wafer Bonding for Microstructure Formation", Proceedings of the IEEE, Vol. 86, No. 8, August 1998.

EXAMINER 	DATE CONSIDERED 1/23/05
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EXAMINER: Initial if citation considered, whether or not citation is in conformance with MPEP § 609; Draw line through citation if not in conformance and not considered. Include copy with next communication to applicant.